

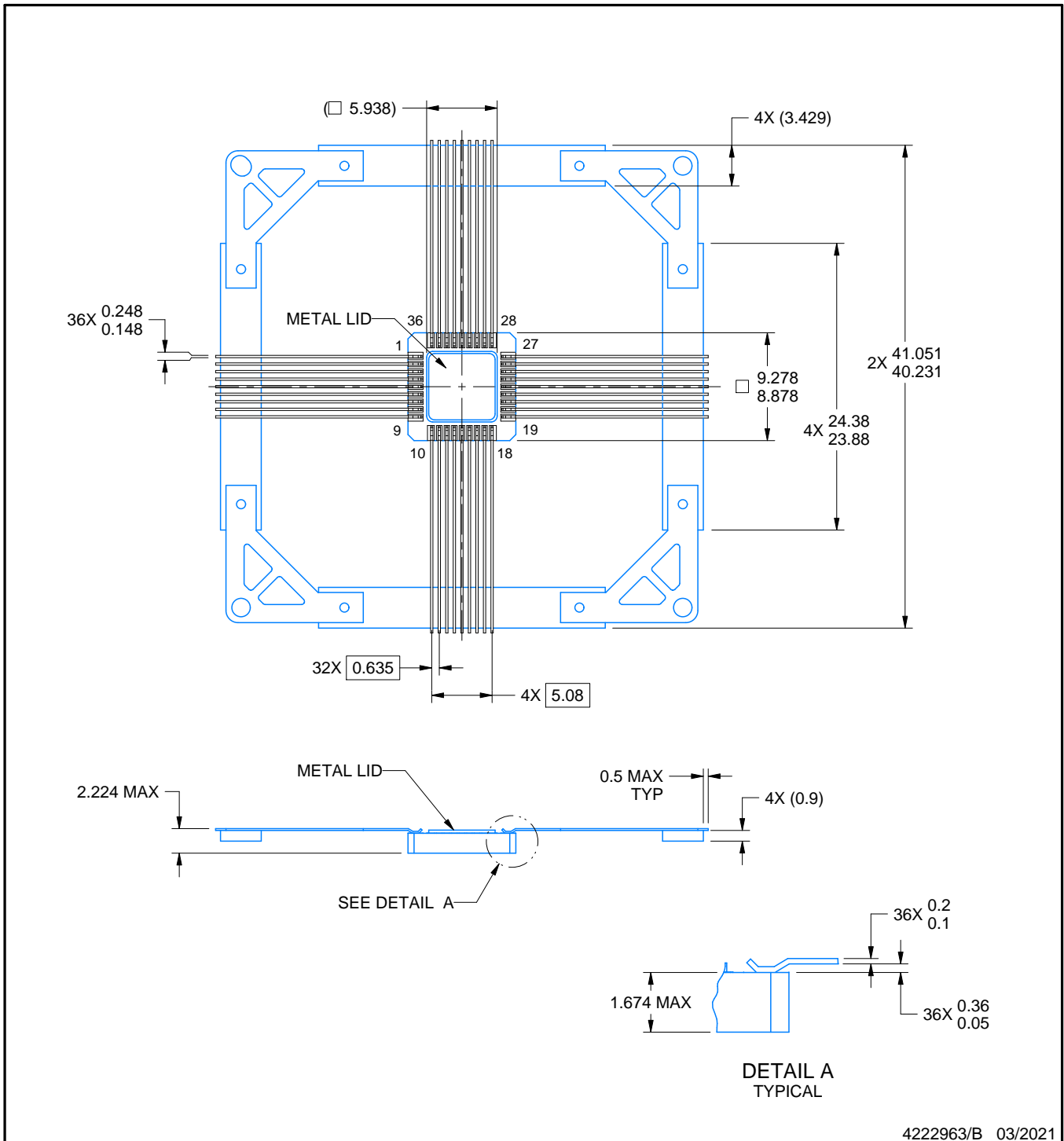


# PACKAGE OUTLINE

## HFG0036A

### CFP - 2.224 mm max height

CERAMIC FLATPACK



4222963/B 03/2021

#### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid.
4. The lid is connected to Pin 8.
5. The leads are gold plated and can be solder dipped.
6. The leads on the top of the package near the lid are showing.

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